October 17, 2008



# **SCAN90004**

# 4-Channel LVDS Buffer/Repeater with Pre-Emphasis and IEEE 1149.6

## **General Description**

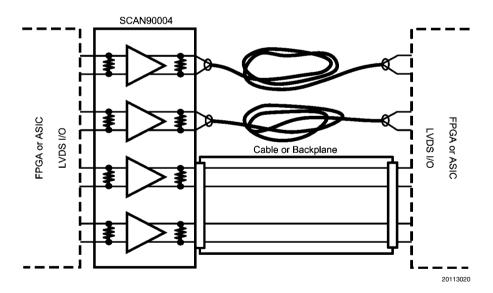
The SCAN90004 is a four channel 1.5 Gbps LVDS buffer/repeater. High speed data paths and flow-through pinout minimize internal device jitter and simplify board layout, while configurable pre-emphasis overcomes ISI jitter effects from lossy backplanes and cables. The differential inputs interface to LVDS, and Bus LVDS signals such as those on National's 10-, 16-, and 18- bit Bus LVDS SerDes, as well as CML and LVPECL. The differential inputs and outputs are internally terminated with a  $100\Omega$  resistor to improve performance and minimize board space. The repeater function is especially useful for boosting signals for longer distance transmission over lossy cables and backplanes.

Integrated IEEE 1149.1 (JTAG) and 1149.6 circuitry supports testability of both single-ended LVTTL/CMOS and high-speed differential LVDS interconnects. The 3.3V supply, CMOS process, and LVDS I/O ensure stable high performance at low power over the entire industrial -40 to +85°C temperature range.

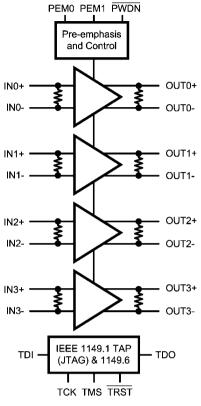
### **Features**

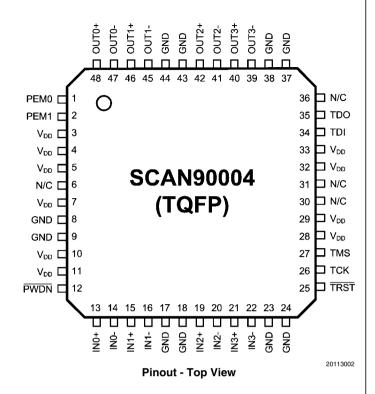
- 1.5 Gbps maximum data rate per channel
- Configurable pre-emphasis drives lossy backplanes and cables
- Low output skew and jitter
- LVDS/CML/LVPECL compatible input, LVDS output
- On-chip 100Ω input and output termination
- 12 kV ESD protection on LVDS Outputs
- IEEE 1149.1 and 1149.6 compliant
- Fault Insertion
- Single 3.3V supply
- Very low power consumption
- Industrial -40 to +85°C temperature range
- Small TQFP Package Footprint
- Evaluation Kit Available
- See DS90LV004 for non-JTAG version

## **Typical Application**



## **Block and Connection Diagrams**





SCAN90004 Block Diagram

# **Pin Descriptions**

Pin	TQFP Pin	I/O, Type	Description	
Name	Number NTIAL INPUTS		·	
INO+	13	LLVDC	Channel Cinyouting and non-invasting differential innuts	
INO+ INO-	13	I, LVDS	Channel 0 inverting and non-inverting differential inputs.	
IN1+	15	I, LVDS	Channel 1 inverting and non-inverting differential inputs.	
IN1+ IN1-	16	I, LVD3	Chainer i inverting and non-inverting differential inputs.	
IN2+	19	I, LVDS	Channel 2 inverting and non-inverting differential inputs.	
IN2-	20	1, 2750	To harmon 2 involving and non-involving amoronical inputs.	
IN3+	21	I, LVDS	Channel 3 inverting and non-inverting differential inputs.	
IN3-	22	, -	The state of the s	
DIFFERE	NTIAL OUTPUTS	·		
OUT0+	48	O, LVDS	Channel 0 inverting and non-inverting differential outputs. (Note 1)	
OUT0-	47			
OUT1+	46	O, LVDS	Channel 1 inverting and non-inverting differential outputs. (Note 1)	
OUT1-	45			
OUT2+	42	O, LVDS	Channel 2 inverting and non-inverting differential outputs. (Note 1)	
OUT2-	41			
OUT3+	40	O, LVDS	Channel 3 inverting and non-inverting differential outputs. (Note 1)	
OUT3-	39			
	CONTROL INTERFACE			
PWDN	12	I, LVTTL	A logic low at PWDN activates the hardware power down mode.	
PEM0	1	I, LVTTL	Pre-emphasis Control Inputs (affects all Channels)	
PEM1	2			
TDI	34	I, LVTTL	Test Data Input to support IEEE 1149.1 features	
TDO	35	O, LVTTL	Test Data Output to support IEEE 1149.1 features	
TMS	27	I, LVTTL	Test Mode Select to support IEEE 1149.1 features	
TCK	26	I, LVTTL	Test Clock to support IEEE 1149.1 features	
TRST	25	I, LVTTL	Test Reset to support IEEE 1149.1 features	
POWER				
$V_{DD}$	3, 4, 5, 7, 10, 11, 28, 29, 32, 33	I, Power	$V_{DD} = 3.3V, \pm 5\%$	
GND	8, 9, 17, 18, 23, 24, 37, 38, 43, 44	I, Power	Ground	
N/C	6, 30, 31, 36		No Connect	

Note 1: The LVDS outputs do not support a multidrop (BLVDS) environment. The LVDS output characteristics of the SCAN90004 device have been optimized for point-to-point backplane and cable applications.

## **Absolute Maximum Ratings** (Note 2)

Supply Voltage (V<sub>DD</sub>) -0.3V to +4.0V **CMOS Input Voltage** -0.3V to  $(V_{DD}+0.3V)$ LVDS Input Voltage (Note 3) -0.3V to  $(V_{DD}+0.3V)$ LVDS Output Voltage -0.3V to  $(V_{DD}+0.3V)$ LVDS Output Short Circuit Current +40 mA Junction Temperature +150°C -65°C to +150°C Storage Temperature Lead Temperature (Solder, 4sec) 260°C Max Pkg Power Capacity @ 25°C 1.64W Thermal Resistance  $(\theta_{JA})$ 76°C/W

ESD Last Passing Voltage (LVDS output pins)

Package Derating above +25°C

HBM, 1.5kΩ, 100pF 12kV EIAJ, 0Ω, 200pF 250V

ESD Last Passing Voltage (All other pins)

HBM, 1.5kΩ, 100pF 8kV EIAJ, 0Ω, 200pF 250V

# Recommended Operating Conditions

 $\begin{array}{lll} \text{Supply Voltage (V}_{\text{CC}}) & 3.15 \text{V to } 3.45 \text{V} \\ \text{Input Voltage (V}_{\text{I}}) \text{ (Note 3)} & 0 \text{V to V}_{\text{CC}} \\ \text{Output Voltage (V}_{\text{O}}) & 0 \text{V to V}_{\text{CC}} \end{array}$ 

Operating Temperature (T<sub>A</sub>)

Industrial –40°C to +85°C

**Note 2:** Absolute maximum ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. National does not recommend operation of products outside of recommended operation conditions

**Note 3:** V<sub>ID</sub> max < 2.4V

### **Electrical Characteristics**

Over recommended operating supply and temperature ranges unless other specified.

13.2mW/°C

Symbol	Parameter	Conditions	Min	Typ (Note 4)	Max	Units	
LVTTL DC SPECIFICATIONS (PWDN, PEM0, PEM1, TDI, TDO, TCK, TMS, TRST)							
V <sub>IH</sub>	High Level Input Voltage		2.0		$V_{DD}$	V	
V <sub>IL</sub>	Low Level Input Voltage		GND		8.0	V	
I <sub>IH</sub>	High Level Input Current	$V_{IN} = V_{DD} = V_{DDMAX}$	-10		+10	μA	
I <sub>IL</sub>	Low Level Input Current	$V_{IN} = V_{SS}, V_{DD} = V_{DDMAX}$	-10		+10	μΑ	
I <sub>ILR</sub>	Low Level Input Current	TDI, TMS, TRST	-40		-200	μΑ	
C <sub>IN1</sub>	Input Capacitance	Any Digital Input Pin to V <sub>SS</sub>		3.5		pF	
C <sub>OUT1</sub>	Output Capacitance	Any Digital Output Pin to V <sub>SS</sub>		5.5		pF	
V <sub>CL</sub>	Input Clamp Voltage	$I_{CL} = -18 \text{ mA}$	-1.5	-0.8		V	
V <sub>OH</sub>	High Level Output Voltage	$I_{OH} = -12 \text{ mA}, V_{DD} = 3.15 \text{ V}$	2.4			V	
	(TDO)	$I_{OH} = -100 \ \mu A, \ V_{DD} = 3.15 \ V$	V <sub>DD</sub> -0.2			V	
V <sub>OL</sub>	Low Level Output Voltage	$I_{OL} = 12 \text{ mA}, V_{DD} = 3.15 \text{ V}$			0.5	V	
	(TDO)	$I_{OL} = 100 \mu\text{A},  V_{DD} = 3.15 \text{V}$			0.2	V	
I <sub>os</sub>	Output Short Circuit Current	TDO	-15		-125	mA	
I <sub>OZ</sub>	Output TRI-STATE Current	TDO	-10		+10	μΑ	
LVDS INP	UT DC SPECIFICATIONS (INn±)			,,			
V <sub>TH</sub>	Differential Input High Threshold (Note 5)	$V_{CM} = 0.8V \text{ to } 3.4V,$ $V_{DD} = 3.45V$		0	100	mV	
V <sub>TL</sub>	Differential Input Low Threshold (Note 5)	$V_{CM} = 0.8V \text{ to } 3.4V,$ $V_{DD} = 3.45V$	-100	0		mV	
$\overline{V_{ID}}$	Differential Input Voltage	$V_{CM} = 0.8V \text{ to } 3.4V, V_{DD} = 3.45V$	100		2400	mV	
V <sub>CMR</sub>	Common Mode Voltage Range	V <sub>ID</sub> = 150 mV, V <sub>DD</sub> = 3.45V	0.05		3.40	V	
C <sub>IN2</sub>	Input Capacitance	IN+ or IN- to V <sub>SS</sub>		5.2		pF	
I <sub>IN</sub>	Input Current	$V_{IN} = 3.45V$ , $V_{DD} = V_{DDMAX}$	-10		+10	μΑ	
		$V_{IN} = 0V, V_{DD} = V_{DDMAX}$	-10		+10	μΑ	

Symbol	Parameter	Conditions	Min	Typ (Note 4)	Max	Units
LVDS OU	TPUT DC SPECIFICATIONS (OU	Tn±)				
V <sub>OD</sub>	Differential Output Voltage, 0% Pre-emphasis (Note 5)	$R_L$ = 100 $\Omega$ external resistor between OUT+ and OUT-	250	500	600	mV
$\Delta V_{OD}$	Change in V <sub>OD</sub> between Complementary States				35	mV
V <sub>os</sub>	Offset Voltage (Note 6)		1.05	1.18	1.475	V
ΔV <sub>OS</sub>	Change in V <sub>OS</sub> between Complementary States		-35		35	mV
I <sub>os</sub>	Output Short Circuit Current	OUT+ or OUT- Short to GND		-60	-90	mA
C <sub>OUT2</sub>	Output Capacitance	OUT+ or OUT- to GND when TRI-STATE		5.5		pF
	CURRENT (Static)			•		•
I <sub>cc</sub>	Supply Current	All inputs and outputs enabled and active, terminated with external differential load of $100\Omega$ between OUT+ and OUT-, 0% pre-emphasis		117	140	mA
I <sub>CCZ</sub>	Supply Current - Power Down Mode	PWDN = L, 0% pre-emphasis		2.7	6	mA
SWITCHII	NG CHARACTERISTICS—LVDS	OUTPUTS				
t <sub>LHT</sub>	Differential Low to High Transition Time	Use an alternating 1 and 0 pattern at 200 Mb/s, measure between 20% and 80% of V <sub>OD</sub> . (Note		210	300	ps
t <sub>HLT</sub>	Differential High to Low Transition Time	11)		210	300	ps
t <sub>PLHD</sub>	Differential Low to High Propagation Delay	Use an alternating 1 and 0 pattern at 200 Mb/s, measure at 50% V <sub>OD</sub> between input to output.		2.0	3.2	ns
t <sub>PHLD</sub>	Differential High to Low Propagation Delay			2.0	3.2	ns
t <sub>SKD1</sub>	Pulse Skew	It <sub>PLHD</sub> -t <sub>PHLD</sub> I (Note 11)		25	80	ps
t <sub>SKCC</sub>	Output Channel to Channel Skew	Difference in propagation delay (t <sub>PLHD</sub> or t <sub>PHLD</sub> ) among all output channels. (Note 11)		50	125	ps
t <sub>SKP</sub>	Part to Part Skew (Note 11)	Common edge, parts at same temp and V <sub>CC</sub> (Note 11)			1.1	ns
t <sub>JIT</sub>	Jitter (0% Pre-emphasis)	RJ - Alternating 1 and 0 at 750 MHz (Note 8)		1.1	1.5	psrms
	(Note 7)	DJ - K28.5 Pattern, 1.5 Gbps (Note 9)		43	62	psp-p
		TJ - PRBS 2 <sup>23</sup> -1 Pattern, 1.5 Gbps (Note 10)		35	85	psp-p
t <sub>ON</sub>	LVDS Output Enable Time	Time from PWDN to OUT± change from TRI-STATE to active.			300	ns
t <sub>OFF</sub>	LVDS Output Disable Time	Time from PWDN to OUT± change from active to TRI-STATE.			12	ns

Symbol	Parameter	Conditions	Min	Typ (Note 4)	Max	Units			
SWITCHI	SWITCHING CHARACTERISTICS—SCAN FEATURES								
f <sub>MAX</sub>	Maximum TCK Clock Frequency	$R_L = 500\Omega$ ,	25.0			MHz			
t <sub>S</sub>	TDI to TCK, H or L	$R_L = 500\Omega$ , $C_L = 35 pF$	3.0			ns			
t <sub>H</sub>	TDI to TCK, H or L		0.5			ns			
$\overline{t_S}$	TMS to TCK, H or L		2.5			ns			
t <sub>H</sub>	TMS to TCK, H or L		0.5			ns			
t <sub>W</sub>	TCK Pulse Width, H or L		10.0			ns			
t <sub>W</sub>	TRST Pulse Width, L		2.5			ns			
t <sub>REC</sub>	Recovery Time, TRST to TCK		1.0			ns			

- Note 4: Typical parameters are measured at  $V_{DD} = 3.3V$ ,  $T_A = 25^{\circ}C$ . They are for reference purposes, and are not production-tested.
- $\textbf{Note 5:} \ \ \textbf{Differential output voltage} \ \ V_{\text{OD}} \ \ \textbf{is defined as ABS(OUT+-OUT-)}. \ \ \textbf{Differential input voltage} \ \ V_{\text{ID}} \ \ \textbf{is defined as ABS(IN+-IN-)}.$
- $\textbf{Note 6:} \ \text{Output offset voltage V}_{\text{OS}} \ \text{is defined as the average of the LVDS single-ended output voltages at logic high and logic low states.}$
- Note 7: Jitter is not production tested, but guaranteed through characterization on a sample basis.
- Note 8: Random Jitter, or RJ, is measured RMS with a histogram including 1500 histogram window hits. The input voltage =  $V_{ID}$  = 500mV, 50% duty cycle at 750MHz,  $t_r$  =  $t_I$  = 50ps (20% to 80%).
- **Note 9:** Deterministic Jitter, or DJ, is measured to a histogram mean with a sample size of 350 hits. The input voltage =  $V_{ID}$  = 500mV, K28.5 pattern at 1.5 Gbps,  $t_r = t_f$  = 50ps (20% to 80%). The K28.5 pattern is repeating bit streams of (0011111010 1100000101).
- Note 10: Total Jitter, or TJ, is measured peak to peak with a histogram including 3500 window hits. Stimulus and fixture jitter has been subtracted. The input voltage =  $V_{ID}$  = 500mV, 2<sup>23</sup>-1 PRBS pattern at 1.5 Gbps,  $t_r = t_f$  = 50ps (20% to 80%).
- Note 11: Not production tested. Guaranteed by a statistical analysis on a sample basis at the time of characterization.

## **Feature Descriptions**

#### INTERNAL TERMINATIONS

The SCAN90004 has integrated termination resistors on both the input and outputs. The inputs have a  $100\Omega$  resistor across the differential pair, placing the receiver termination as close as possible to the input stage of the device. The LVDS outputs also contain an integrated  $100\Omega$  ohm termination resistor, this resistor is used to reduce the effects of Near End Crosstalk (NEXT) and does not take the place of the 100 ohm termination at the inputs to the receiving device. The integrated terminations improve signal integrity and decrease the external component count resulting in space savings.

#### **OUTPUT CHARACTERISTICS**

The output characteristics of the SCAN90004 have been optimized for point-to-point backplane and cable applications, and are not intended for multipoint or multidrop signaling.

#### **POWERDOWN MODE**

The PWDN input activates a hardware powerdown mode. When the powerdown mode is active (PWDN=L), all input and output buffers and internal bias circuitry are powered off and disabled. Outputs are tri-stated in powerdown mode. JTAG Circuitry is active per the IEEE standard, but does not switch unless TCK is toggling. When exiting powerdown mode, there is a delay associated with turning on bandgap references and input/output buffer circuits as indicated in the LVDS Output Switching Characteristics

#### **PRE-EMPHASIS**

Pre-emphasis dramatically reduces ISI jitter from long or lossy transmission media. Two pins are used to select the pre-emphasis level for all outputs: off, low, medium, or high.

#### **Pre-emphasis Control Selection Table**

PEM1	PEM0	Pre-Emphasis
0	0	Off
0	1	Low
1	0	Medium
1	1	High

#### **INPUT FAILSAFE BIASING**

External pull up and pull down resistors may be used to provide enough of an offset to enable an input failsafe under open-circuit conditions. This configuration ties the positive LVDS input pin to  $V_{DD}$  thru a pull up resistor and the negative LVDS input pin is tied to GND by a pull down resistor. The pull up and pull down resistors should be in the  $5k\Omega$  to  $15k\Omega$  range to minimize loading and waveform distortion to the driver. The common-mode bias point ideally should be set to approximately 1.2V (less than 1.75V) to be compatible with the internal circuitry. Please refer to application note AN-1194 "Failsafe Biasing of LVDS Interfaces" for more information.

## **Design-for-Test (DfT) Features**

#### **IEEE 1149.1 (JTAG) SUPPORT**

The SCAN90004 supports a fully compliant IEEE 1149.1 interface. The Test Access Port (TAP) provides access to boundary scan cells at each LVTTL I/O on the device for interconnect testing. Differential pins are included in the same boundary scan chain but instead contain IEEE1149.6 cells. IEEE1149.6 is the improved IEEE standard for testing high-speed differential signals.

Refer to the BSDL file located on National's website for the details of the SCAN90004 IEEE 1149.1 implementation.

#### **IEEE 1149.6 SUPPORT**

AC-coupled differential interconnections on very high speed (1+ Gbps) data paths are not testable using traditional IEEE 1149.1 techniques. The IEEE 1149.1 structures and methods are intended to test static (DC-coupled), single ended networks. IEEE1149.6 is specifically designed for testing high-speed differential, including AC coupled networks.

The SCAN90004 is intended for high-speed signalling up to 1.5 Gbps and includes IEEE1149.6 on all differential inputs and outputs.

#### **FAULT INSERTION**

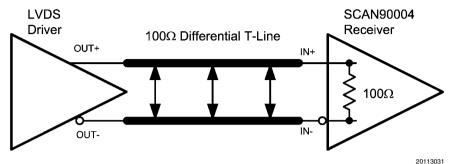
Fault Insertion is a technique used to assist in the verification and debug of diagnostic software. During system testing faults are "injected" to simulate hardware failure and thus help verify the monitoring software can detect and diagnose these faults. In the SCAN90004 an IEEE1149.1 "stuck-at" instruction can create a stuck-at condition, either high or low, on any pin or combination of pins. A more detailed description of the stuck-at feature can be found in NSC Applications note AN-1313.

## **Application Information**

#### INPUT INTERFACING

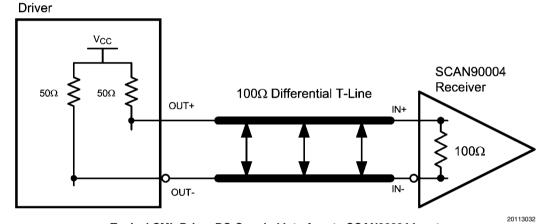
The SCAN90004 accepts differential signals and allow simple AC or DC coupling. With a wide common mode range, the

SCAN90004 can be DC-coupled with all common differential drivers (i.e. LVPECL, LVDS, CML). The following three figures illustrate typical DC-coupled interface to common differential drivers. Note that the SCAN90004 inputs are internally terminated with a  $100\Omega$  resistor.



Typical LVDS Driver DC-Coupled Interface to SCAN90004 Input

CML3.3V or CML2.5V



Typical CML Driver DC-Coupled Interface to SCAN90004 Input

LVPECL Driver  $100\Omega$  Differential T-Line  $100\Omega$  Differential T-Line  $100\Omega$ 

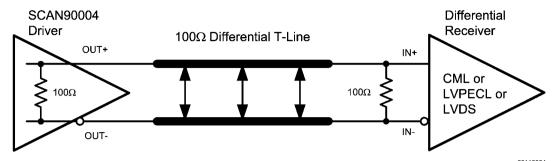
Typical LVPECL Driver DC-Coupled Interface to SCAN90004 Input

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#### **OUTPUT INTERFACING**

The SCAN90004 outputs signals that are compliant to the LVDS standard. Their outputs can be DC-coupled to most common differential receivers. The following figure illustrates typical DC-coupled interface to common differential receivers

and assumes that the receivers have high impedance inputs. While most differential receivers have a common mode input range that can accommodate LVDS compliant signals, it is recommended to check respective receiver's data sheet prior to implementing the suggested interface implementation.

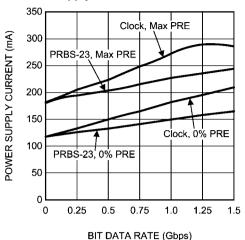


Typical SCAN90004 Output DC-Coupled Interface to an LVDS, CML or LVPECL Receiver

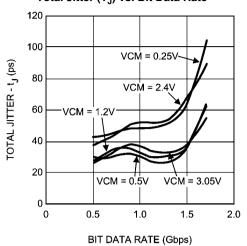
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## **Typical Performance Characteristics**

#### Power Supply Current vs. Bit Data Rate



#### Total Jitter (T<sub>.I</sub>) vs. Bit Data Rate

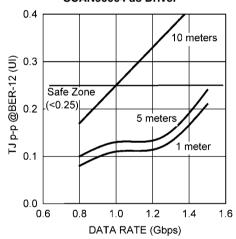


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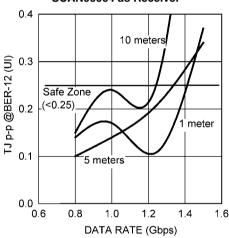
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Dynamic power supply current was measured while running a clock or PRBSTotal Jitter measured at 0V differential while running a PRBS  $2^{23}$ -1 pattern with  $2^{23}$ -1 pattern with all 4 channels active.  $V_{CC} = 3.3V$ ,  $T_A = +25^{\circ}C$ ,  $V_{ID} = 0.5V$ , a single channel active.  $V_{CC} = 3.3V$ ,  $T_A = +25^{\circ}C$ ,  $V_{ID} = 0.5V$ ,  $V_{ID} = 0.5V$ , a single channel active.  $V_{CC} = 3.3V$ ,  $V_{$ 

# Total Jitter (U.I.) vs. Bit Data Rate SCAN90004 as Driver



# Total Jitter (U.I.) vs. Bit Data Rate SCAN90004 as Receiver

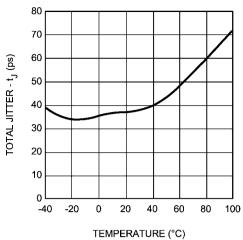


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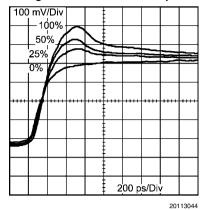
Total Jitter measured while SCAN90004 output is driving a PRBS  $2^7$ -1 NRZ pat-Total Jitter measured at SCAN90004 receiver outputs after receiving a PRBS tern with a single active channel across a Belden 1700A cable.  $V_{CC} = 3.3V$ ,  $T_A = 2^7$ -1 NRZ pattern over the specified cable length.  $V_{CC} = 3.3V$ ,  $T_A = +25^{\circ}C$ ,  $V_{ID} = +25^{\circ}C$ ,  $V_{ID} = 0.5V$ ,  $0^{\circ}C$  Pre-emphasis. Data measured at end of specified cable0.5V, data collected at receiver outputs, receiver located at end of specified length.

## Total Jitter (T<sub>J</sub>) vs. Temperature

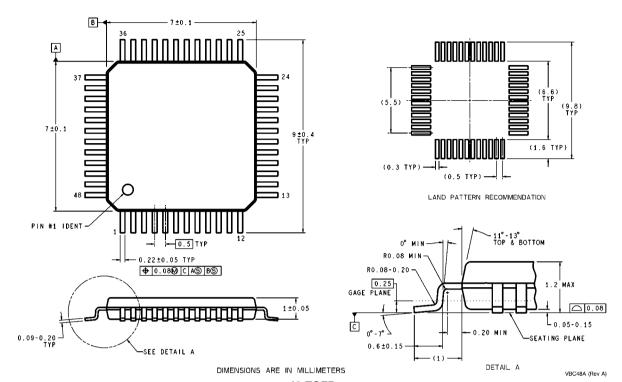


Total Jitter measured at 0V differential while running a PRBS 223-1 pattern with a single channel active.  $V_{CC}$  = 3.3V,  $V_{ID}$  = 0.5V,  $V_{CM}$  = 1.2V, 1.5 Gbps data rate, 0% Pre-emphasis

#### Positive Edge Transition vs. Pre-emphasis Level



# Physical Dimensions inches (millimeters) unless otherwise noted



48-TQFP NS Package Number VBC48a Order Number SCAN90004TVS (250 piece Tray)

## **Notes**

For more National Semiconductor product information and proven design tools, visit the following Web sites at:

Pr	oducts	Design Support		
Amplifiers	www.national.com/amplifiers	WEBENCH	www.national.com/webench	
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Data Converters	www.national.com/adc	Distributors	www.national.com/contacts	
Displays	www.national.com/displays	Green Compliance	www.national.com/quality/green	
Ethernet	www.national.com/ethernet	Packaging	www.national.com/packaging	
Interface	www.national.com/interface	Quality and Reliability	www.national.com/quality	
LVDS	www.national.com/lvds	Reference Designs	www.national.com/refdesigns	
Power Management	www.national.com/power	Feedback	www.national.com/feedback	
Switching Regulators	www.national.com/switchers			
LDOs	www.national.com/ldo			
LED Lighting	www.national.com/led			
PowerWise	www.national.com/powerwise			
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